

GUH Circuit Industry (PG) Sdn Bhd

MULTILAYER CAPABILITIES

Capabilities (能力)	MP Capabilities (量产能力)	Sample Capabilities (样品能力)
Layer Count (最大层数)	2 ~ 10 Layers	2 ~ 16 Layers
PCB Thickness (板厚范围)	0.4mm ~ 3.2mm	0.3mm ~ 3.2mm
Layer Registration (层间对位)	125μm	100μm
Minimum Mechanical Drill Size (最小钻径)	0.15mm (150μm)	0.15mm (150μm)
Hole Diameter Tolerance (孔径公差)	PTH ± 75μm / NPTH ± 50μm	PTH ± 50μm / NPTH ± 37.5μm
Drill Hole Accuracy (孔位精度)	± 50μm	± 37.5μm
Plating Aspect Ratio (电镀纵横比)	12 : 1	14 : 1
Copper Thickness (铜厚范围)	1oz , 2oz, 3oz, 5oz	1oz , 2oz, 3oz, 5oz
Minimum Line Width / Spacing (最小线宽/线距)	75μm / 75μm	75μm / 75μm
Solder Mask Registration (阻焊对位精度)	± 50μm	± 37.5μm
Minimum Solder Mask Bridge (最小阻焊桥)	Green/Red ± 75μm Blue/Black ± 100μm	Green/Red ± 75μm Blue/Black ± 100μm
CNC Tolerance (成型尺寸精度)	± 100μm	± 100μm
CNC Process (成型加工) • Hole to Edge (孔到板边) • Edge to Edge (边到板边) • Circuit to Edge (线路到板边)	± 0.25mm ± 0.10mm ± 0.10mm	± 0.25mm ± 0.10mm ± 0.10mm
Maximum PCB Size (最大生产板尺寸)	520mm X 620mm	520mm X 620mm
Minimum PCB Size (最小生产板尺寸)	16mm X 16mm	16mm X 16mm
Surface Finishing (表面处理)	OSP, ENIG, Hard Gold, HASL, Carbon, Peelable Mask, Selective Surface	OSP, ENIG, Hard Gold, HASL, Carbon, Peelable Mask, Selective Surface
Impedance Control Tolerance (阻抗公差)	± 10%	± 10%
Special Capability (特殊工艺)	-	Non-wire Gold Finger, Hybrid Material, Sequential Lamination

~ The above production capabilities serve as a general guideline and is subject to change ~